

SPECIFICATION AGM 12864A-801

Atualizado em 05/06/19.

MODLE NO:

AGM 12864A-801

RECORDS OF REVISION VERSION DATE REVISED PAGE NO			DOC. FIRST ISSUE
VERSION	DATE	REVISED PAGE NO.	SUMMARY
0	2011/01/24		First issue
A	2013/06/04		Remove IC information
В	2013/07/05		Modify screw hole

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1.Precautions in use of LCD Modules

- (1) Avoid applying excessive shocks to the module or making any alterations or modifications to it.
- (2)Don't make extra holes on the printed circuit board, modify its shape or change the components of LCD module.
- (3) Don't disassemble the LCM.
- (4) Don't operate it above the absolute maximum rating.
- (5)Don't drop, bend or twist LCM.
- (6) Soldering: only to the I/O terminals.
- (7) Storage: please storage in anti-static electricity container and clean environment.
- (8) AGT have the right to change the passive components, including R3,R6 & backlight adjust resistors. (Resistors, capacitors and other passive components will have different appearance and color caused by the different supplier.)
- (9) AGT have the right to change the PCB Rev. (In order to satisfy the supplying stability, management optimization and the best product performance...etc, under the premise of not affecting the electrical characteristics and external dimensions, AGT have the right to modify the version.)

2.General Specification

Item	Dimension	Unit			
Number of dots	128 x 64	_			
Module dimension	93.0 x 70.0 x 13.6 (MAX)	mm			
View area	72.0 x 40.0	mm			
Active area	66.52 x 33.24	mm			
Dot size	0.48 x 0.48	mm			
Dot pitch	0.52 x 0.52	mm			
LCD type	STN Negative, Blue Transmissive (In LCD production, It will occur slightly color difference. We can only guarantee the same color in the same batch.)				
Duty	1/64				
View direction	6 o'clock				
Backlight Type	LED, White				
IC	NT7107, NT7108				

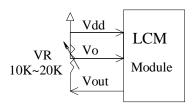
3.Absolute Maximum Ratings

Item	Symbol	Min	Тур	Max	Unit
Operating Temperature	T_{OP}	-20	_	+70	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	-30	_	+80	$^{\circ}\! \mathbb{C}$
Supply Voltage For Logic	V_{DD} - V_{SS}	-0.3	_	7.0	V
Driver Supply Voltage	$V_{ m LCD}$	V _{EE} -0.3	_	V _{DD} +0.3	V

4.Electrical Characteristics

ITEM	SYMBOL	CONDITION	MIN.	TYP.	MAX.	UNIT
Supply Voltage For Logic	$V_{ m DD} ext{-}V_{ m SS}$	_	4.5	5.0	5.5	V
Supply Voltage For		Ta=-20°C			10.6	V
LCD	V_{DD} - V_{O}	Ta=25°C	8.6	8.9	9.2	V
*Note		Ta=70°C	7.6			V
Input High Volt.	V_{IH}	_	$0.7~V_{DD}$	1	V_{DD}	V
Input Low Volt.	V_{IL}	_	0		0.8	V
Output High Volt.	V_{OH}	_	2.4		1	V
Output Low Volt.	V_{OL}	_			0.4	V
Supply Current	I_{DD}	V _{DD} =5.0V	_	29.2	_	mA

^{*} Note: Please design the VOP adjustment circuit on customer's main board

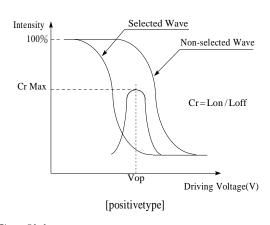


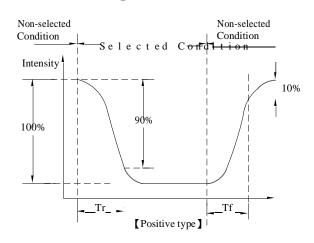
5.Optical Characteristics

Item	Symbol	Condition	Min	Тур	Max	Unit
	θ	CR≧2	0	_	20	$\psi = 180^{\circ}$
Wan Anala	θ	CR≧2	0	_	40	$\Psi = 0^{\circ}$
View Angle	θ	CR≧2	0	_	30	$\Psi = 90^{\circ}$
	θ	CR≧2	0	_	30	$\psi = 270^{\circ}$
Contrast Ratio	CR	_	_	3	_	_
D Time	T rise	_	_	150	200	ms
Response Time	T fall	_	_	150	20 40 30 30 —	ms

Definition of Operation Voltage (Vop)

Definition of Response Time (Tr, Tf)





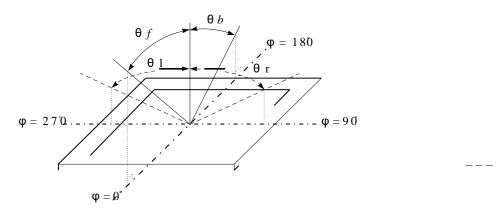
Conditions:

Operating Voltage: Vop

Viewing Angle(θ , ϕ): 0° , 0°

Frame Frequency: 64 HZ Driving Waveform: 1/N duty, 1/a bias

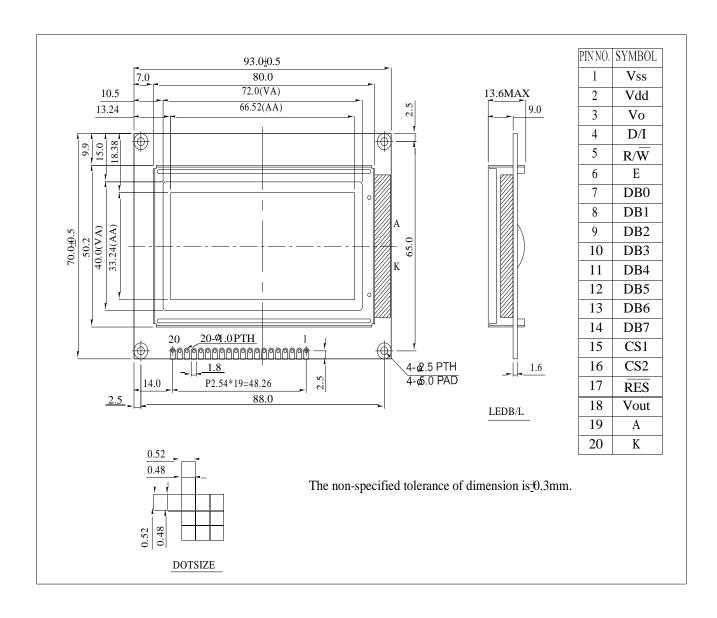
Definition of viewing angle ($CR \ge 2$)

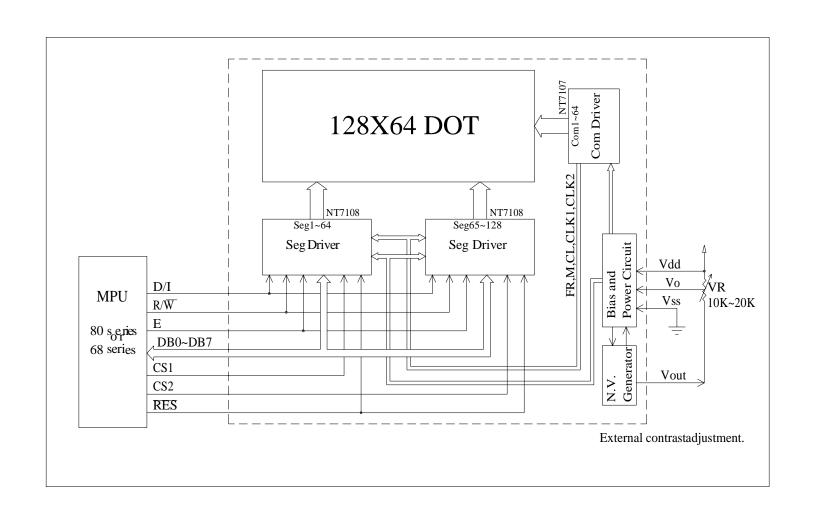


6.Interface Pin Function

Pin No.	Symbol	Level	Description
1	V _{SS}	0V	Ground
2	V_{DD}	5.0V	Supply voltage for logic
3	Vo	(Variable)	Operating voltage for LCD
4	D/I	H/L	H: Data, L: Instruction
5	R/W	H/L	H: Read (MPU←Module) , L: Write (MPU→Module)
6	Е	Н	Enable signal
7	DB0	H/L	Data bus line
8	DB1	H/L	Data bus line
9	DB2	H/L	Data bus line
10	DB3	H/L	Data bus line
11	DB4	H/L	Data bus line
12	DB5	H/L	Data bus line
13	DB6	H/L	Data bus line
14	DB7	H/L	Data bus line
15	CS1	Н	Select Column 1~ Column 64
16	CS2	Н	Select Column 65~ Column 128
17	/RES	L	Reset signal
18	Vout	_	Negative Voltage output
19	A	_	Power Supply for LED backlight (+)
20	K	_	Power Supply for LED backlight (-)

7.Contour Drawing & Block Diagram





8.Reliability

Content of Reliability Test (Wide temperature, -20°C~70°C)

	Environmental Test		
Test Item	Content of Test	Test Condition	Note
High Temperature storage	Endurance test applying the high storage temperature for a long time.	80°C 200hrs	2
Low Temperature storage	Endurance test applying the low storage temperature for a long time.	-30°C 200hrs	1,2
High Temperature Operation	Endurance test applying the electric stress (Voltage & Current) and the thermal stress to the element for a long time.	70°C 200hrs	
Low Temperature Operation	Endurance test applying the electric stress under low temperature for a long time.	-20°C 200hrs	1
High Temperature/ Humidity storage	The module should be allowed to stand at 60 °C,90% RH max For 96hrs under no-load condition excluding the polarizer, Then taking it out and drying it at normal temperature.	60°C,90%RH 96hrs	1,2
Thermal shock resistance	The sample should be allowed stand the following 10 cycles of operation -20°C 25°C 70°C	-20°C/70°C 10 cycles	
Vibration test	Endurance test applying the vibration during transportation and using.	Total fixed amplitude: 1.5mm Vibration Frequency: 10~55Hz One cycle 60 seconds to 3 directions of X,Y,Z for Each 15 minutes	3
Static electricity test	Endurance test applying the electric stress to the terminal.	VS=800V,RS=1.5k Ω CS=100pF 1 time	

Note1: No dew condensation to be observed.

Note2: The function test shall be conducted after 4 hours storage at the normal

Temperature and humidity after remove from the test chamber.

Note3: The packing have to including into the vibration testing.

9. Backlight Information

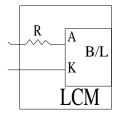
Specification

PARAMETER	SYMBOL	MIN	TYP	MAX	UNIT	TEST CONDITION
Supply Current	ILED	-	64	80	mA	V=3.5V
Supply Voltage	V	3.4	3.5	3.6	V	-
Reverse Voltage	VR	-	-	5	V	-
Luminance (Without LCD)	IV	440	550	-	CD/M ²	ILED=64mA
LED Life Time (For Reference only)	-	-	50K	-	Hr.	ILED=64mA 25°C,50-60%RH, (Note 1)
Color	White		1	- 1	1	

Note: The LED of B/L is drive by current only, drive voltage is for reference only. drive voltage can make driving current under safety area (current between minimum and maximum).

Note 1:50K hours is only an estimate for reference.

.Drive from pin19,pin20



10.Inspection specification

NO	Item	Criterion				AQL	
01	Electrical Testing	Missing vertical, horizontal segment, segment contrast defect. Missing character, dot or icon. Display malfunction. No function or no display. Current consumption exceeds product specifications. LCD viewing angle defect. Mixed product types. Contrast defect.					
02	Black or white spots on LCD (display only)	 2.1 White and black spots on display ≤0.25mm, no more than three white or black spots present. 2.2 Densely spaced: No more than two spots or lines within 3mm 					
03	LCD black spots, white spots, contamination (non-display)	3.1 Round type $\Phi=(x+y)/2$ X 3.2 Line type:	¥ ▼Y	SIZE $\Phi \le 0.10$ $0.10 < \Phi \le 0.20$ $0.20 < \Phi \le 0.25$ $0.25 < \Phi$	Acceptable Q TY Accept no dense 2 1 0 Acceptable Q TY Acceptable Q TY Accept no dense 2 As round type	2.5	
04	Polarizer bubbles	If bubbles are v judge using bla specifications, to to find, must ch specify directio	ck spot not easy neck in	Size Φ $ Φ \le 0.20 $ $ 0.20 < Φ \le 0.50 $ $ 0.50 < Φ \le 1.00 $ $ 1.00 < Φ $ $ Total Q TY$	Acceptable Q TY Accept no dense 3 2 0 3	2.5	

NO	Item	Criterion			AQL
05	Scratches	Follow NO.3 LCD bl	ack spots, white spots, c	ontamination	
		Symbols Define:			
		x: Chip length	y: Chip width z: C	Chip thickness	
		k: Seal width	t: Glass thickness a: L	.CD side length	
		L: Electrode pad leng	th:		
		6.1 General glass chip):		
		6.1.1 Chip on panel s	urface and crack betwee	n panels:	
			Y K		
		z: Chip thickness	y: Chip width	x: Chip length	
		Z≤1/2t	Not over viewing	x≤1/8a	
06	Chipped		area		2.5
	glass	$1/2t < z \leq 2t$	Not exceed 1/3k	x≤1/8a	
		6.1.2 Corner crack: $z: Chip thickness$ $z \le 1/2t$ $1/2t < z \le 2t$	y: Chip width Not over viewing area Not exceed 1/3k	$x: Chip length$ $x \le 1/8a$ $x \le 1/8a$	
		⊙ If there are 2 or mo	ore chips, x is the total le	ngth of each chip.	

NO	Item	Criterion			AQL		
		Symbols: x: Chip length y: Chip width z: Chip thickness k: Seal width t: Glass thickness a: LCD side length L: Electrode pad length 6.2 Protrusion over terminal: 6.2.1 Chip on electrode pad:					
		y: Chip width x: C $y \le 0.5 \text{mm}$ $x \le 1$ 6.2.2 Non-conductive portion	1/8a 0				
06	Glass	y X		L 1 2	2.5		
		y: Chip width	x: Chip length	z: Chip thickness			
		y≦ L	x≤1/8a	$0 < z \le t$			
		 ⊙ If the chipped area touches the ITO terminal, over 2/3 of the ITO must remain and be inspected according to electrode terminal specifications. ⊙ If the product will be heat sealed by the customer, the alignment mark not be damaged. 6.2.3 Substrate protuberance and internal crack. y: width y y <l< td=""></l<>					

NO	Item	Criterion	AQL
07	Cracked glass	The LCD with extensive crack is not acceptable.	2.5
		8.1 Illumination source flickers when lit.	0.65
08	Backlight	8.2 Spots or scratched that appear when lit must be judged.	2.5
00	elements	Using LCD spot, lines and contamination standards.	
		8.3 Backlight doesn't light or color wrong.	0.65
		9.1 Bezel may not have rust, be deformed or have fingerprints,	2.5
09	Bezel	stains or other contamination.	
		9.2 Bezel must comply with job specifications.	0.65
		10.1 COB seal may not have pinholes larger than 0.2mm or contamination.	2.5
		10.2 COB seal surface may not have pinholes through to the IC.	2.5
		10.3 The height of the COB should not exceed the height	0.65
		indicated in the assembly diagram.	
		10.4 There may not be more than 2mm of sealant outside the	2.5
		seal area on the PCB. And there should be no more than three	
		places.	
		10.5 No oxidation or contamination PCB terminals.	2.5
10	PCB · COB	10.6 Parts on PCB must be the same as on the production	0.65
10	102 002	characteristic chart. There should be no wrong parts, missing	
		parts or excess parts.	0.65
		10.7 The jumper on the PCB should conform to the product characteristic chart.	0.65
		10.8 If solder gets on bezel tab pads, LED pad, zebra pad or	2.5
		screw hold pad, make sure it is smoothed down.	
		10.9 The Scraping testing standard for Copper Coating of PCB	2.5
		\mathbf{X} $\mathbf{X} * \mathbf{Y} \leq 2 \text{mm} 2$	
		11.1 No un-melted solder paste may be present on the PCB.	2.5
		11.2 No cold solder joints, missing solder connections,	2.5
11	Soldering	oxidation or icicle.	
		11.3 No residue or solder balls on PCB.	2.5
		11.4 No short circuits in components on PCB.	0.65

NO	Item	Criterion	AQL	
	General appearance	12.1 No oxidation, contamination, curves or, bends on interface		
		Pin (OLB) of TCP.		
		12.2 No cracks on interface pin (OLB) of TCP.		
		123 No contamination, solder residue or solder balls on product.		
		12.4 The IC on the TCP may not be damaged, circuits.		
		125 The uppermost edge of the protective strip on the interface	2.5	
		pin must be present or look as if it cause the interface pin to sever.		
12		12.6 The residual rosin or tin oil of soldering (component or chip	2.5	
		component) is not burned into brown or black color.		
		12.7 Sealant on top of the ITO circuit has not hardened.	2.5	
		12.8 Pin type must match type in specification sheet.	0.65	
		12.9 LCD pin loose or missing pins.	0.65	
		12.10 Product packaging must the same as specified on packaging	0.65	
		specification sheet.		
		12.11 Product dimension and structure must conform to product	0.65	
		specification sheet.		
		12.12 Visual defect outside of VA is not considered to be rejection.	0.65	

11.Material List of Components for RoHs

AGTECHNOLOGIES hereby declares that all of or part of products (with the mark
"#"in code), including, but not limited to, the LCM, accessories or packages, manufactured
and/or delivered to your company (including your subsidiaries and affiliated company)
directly or indirectly by our company (including our subsidiaries or affiliated companies) do
not intentionally contain any of the substances listed in all applicable EU directives and
regulations, including the following substances.

Exhibit A: The Harmful Material List

Material	(Cd)	(Pb)	(Hg)	(Cr6+)	PBBs	PBDEs			
Limited Value	100 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm	1000 ppm			
Above limited value is set up according to RoHS.									

2. Process for RoHS requirement:

- (1) Use the Sn/Ag/Cu soldering surface; the surface of Pb-free solder is rougher than we used before.
- (2) Heat-resistance temp. :

Reflow: 250° C, 30 seconds Max.;

Connector soldering wave or hand soldering : 320°C, 10 seconds max.

(3) Temp. curve of reflow, max. Temp. $: 235\pm5^{\circ}\mathbb{C}$;

Recommended customer's soldering temp. of connector : 280°C, 3 seconds.

12. Recommendable Storage

- 1. Place the panel or module in the temperature 25°C±5°C and the humidity below 65% RH
- 2. Do not place the module near organics solvents or corrosive gases.
- 3. Do not crush, shake, or jolt the module.